

**IEEE Transactions on Electromagnetic Compatibility
Call for Papers**

**Special Section
“Wireless EMC and Wireless EMC/OTA Measurements”**

Wireless technologies are commonly integrated into various electronic designs. EMC issues including receiver desensitization, ESD, modulation/intermodulation, and measurement methodologies for wireless over-the-air (OTA) performance are important to EMC and testing engineers. With the rapid development of Internet of Things and future 5G wireless technologies, our society faces both significant challenges and opportunities.

The special section, promoted by the IEEE EMC Society Technical Committee TC-12 "EMC for Emerging Wireless Technologies", seeks to cover a variety of important topics in the area of wireless EMC and wireless EMC/OTA measurements.

Suggested areas to be covered in the Special Section:

A. Wireless EMC

- A.1 Receiver desensitization: noise from digital platform interferes with the wireless receiver, degrading its sensitivity
- A.2 ESD in wireless devices: a significant issue in cell phone-like devices due to complex geometry and compact size
- A.3 Wireless coexistence: interference/isolation issues among multiple wireless sub-systems
- A.4 Modeling and measurement techniques for wireless EMC characterization
- A.5 Product level EMC debugging
- A.6 Wireless EMC measurement

B. Wireless OTA Measurement

- B.1 Fast and accurate MIMO testing considering self-interference
- B.2 MIMO testing methodologies for self-interference
- B.3 Electromagnetic Absorbing materials and design
- B.4 Modeling techniques for wireless EMC measurement
- B.5 Wireless verification in industry applications

Paper submission deadline: **May 1st , 2017** (later submissions will not be accepted).

Planned publication date: **October 2017**

On-line submission procedure for the authors: use “IEEE TEMC Manuscript Central” as an ordinary TEMC submission; select the paper as “Special Section paper”; insert only the following phrase “for Special Section on Wireless EMC and Wireless EMC/OTA Measurements” in the cover letter field. All papers are to conform to IEEE TEMC Guidelines. Authors are requested to submit papers up to 8 pages in length, including title, author’s affiliation, abstract, and figures.

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